JSCJ

Reliability Report

Report NO.: M-R00012

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC110SN10H
Package Type :	PDFNWB5x6-8L
Part Description :	100V SMDs/MOSFET
Report Date:	February-25

2.Reliability Test Results : PASS

Test Item	Test condition	Duration	Fail Quantity / S.S
Pre-and post-stress Electrical test	Ta=25℃	NA	All parts
PC Precondition(For SMD Package Only)	JESD22-A113F/J-STD-020 1.Bake:125℃. 2.Soak: 85℃85%RH,168hrs MSL1 or 30℃60%RH,192hrs MSL3 3.Reflow 3Cycles Max 260℃ 4.all samples E-Test	>168Hours or >192Hours	0 / 308*3
TCT Temperature Cycling Test	JESD22 -A104 -55℃/15min 150℃/15min	1000cycles	0 / 77*3
AC Autoclave	JESD22-A102 121℃, 100%RH	96Hours	0 / 77*3
UHAST Unbaised Highly Accelerated Stress Test	JESD22-A118 130℃, 85%RH	NA	NA
THT High Humidity &Temp Test	JESD22-A101 85℃ 85%RH	1000Hours	0 / 77*3
HTST High Temperature Storage Test	JESD22 -A103 T=Tstg max	1000Hours	0 / 77*3
H3TRB High Humidity &Temp . Bias Test	JESD22-A101 85℃ 85%RH VDS*80% VR<=100V Max	NA	NA
HAST Highly Accelerated Stress Test	JESD22-A110 130℃ 85%RH VDS*80% VR≦42V Max	96Hours	0 / 77*3
HTRB High Temperature Revers Bias Test	JESD22 -A108 Tj(max) @VDS *80%	1000Hours	0 / 77*3
HTGB High Temperature Gate Bias Test	JESD22 -A108 Tj(max) VR=BVGS*100%	1000Hours	0 / 77*3
IOL Intermittent Operational Life	MIL-STD-750D Method 1037 △Tj≥100℃ On/Off:2min	15000Cycle	0 / 77*3
RSH Resistance to Solder Heat test	JESD22-A111B 260℃±5℃, 10(+2,-0)Seconds	NA	0 / 30*3
SD Solderability	J-STD-002 Steam aging:93℃ 8hour 2.245℃ 3~5s	NA	0 / 10*3

Notes:

1. Either H3TRB or HAST for reliability test.
2. Either AC or UHAST for reliability test.
3. Detailed MSL of the product refers to the MSL Report.

Remark: JSCJ Laboratory reserves the right of final interpretation of this report